

# KubotaComps's Bump Inspection System has realized **highly precise** and **fast speed inspection** for the 100% height measurement of the gold bumps on a wafer by the scanning type white light interference method in our unique measurement

## BUMP INSPECTION SYSTEM



BHT-1000G

Measurement Method	White light interference	
Measurement Object	Wafer size	6inch, 8inch
	Bump size	16 micron or larger
Accuracy	Repeatability	sigma < 0.1micron
Measurement Time	8 inch wafer	about 7 min
Equipment size (mm)	1700 (W) X 1000 (D) X 1940 (H)	

### ■ Feature

- Able to detect deformity such as abnormal projections and partial hiatus of the gold bumps.
- User friendly software for making a recipe within 30 min.
- High power inspection for using a small area as a base level of the bump height measurement, and the three-dimensional shape measurement of the defect bump. (Both of the above function are optional)

### ■ High Precision

- Repeatability SIGMA=0.05 to 0.08 micron

### ■ High Speed

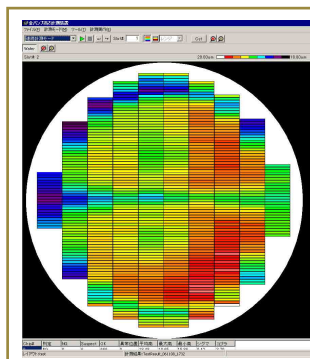
- About 7min for 8 inch wafer (absolute height measurement)

### ■ Narrower Spacing

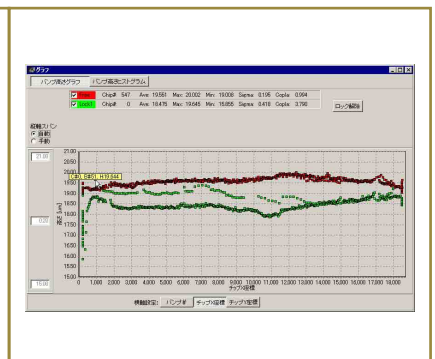
- No limitation by means of changing the objective lens

### ■ Low Bump height

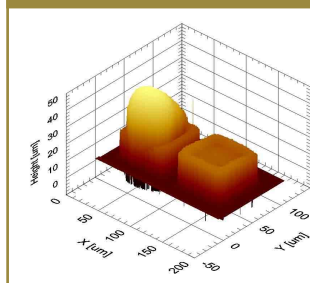
- No limitation



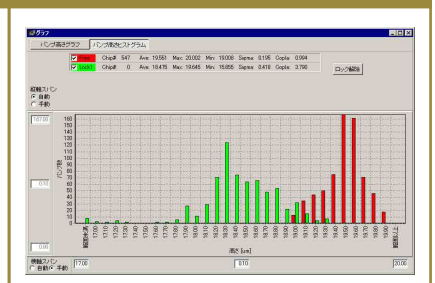
Example of the bump height map by chips



Example of the bump height distribution in a chip



Example of the three-dimensional display of the defect bump



Histogram



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